2017 IEEE 6th Global Conference on Consumer Electronics (GCCE 2017) is asking for submissions of technical papers for Oral, Demo!, and Poster presentations.

The IEEE GCCE 2017 will bring together top technical professionals from the consumer electronics industry and academia to exchange information and results of state-of-the-art work on systems, circuits, technologies, processes and applications! Student papers are particularly encouraged.

Call For Papers!

Oral, Demo!, and Poster categories

Hardware & Software
Digital & Analog

In 2017, GCCE welcomes “Co-design” papers (incl. Human & Computer) with the Best Co-design Awards!

Organizational Sponsors

1. The Institute of Electronics, Information and Communication Engineers (IEICE)
2. The Institute of Electrical Engineers of Japan (JIEE)
3. The Institute of Image Information and Television Engineers (IITV)
4. The Information Processing Society of Japan (IPSJ)
5. Japan Institute of Electronics Engineers of Japan (JIEEE)
6. Japan Institute of Power Electronics (JIEPE)
7. Game Amusement Society (G.A.S.)

Important Dates

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<td>Abstract Proposal of Organized Session</td>
<td>January 30, 2017</td>
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<td>2-pages Review Paper Submission</td>
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Accepted and presented papers will be appeared in IEEE Xplore and the authors are encouraged to submit enhanced journal-quality papers to the IEEE Transactions on Consumer Electronics!
GCCE 2017 Welcomes Organized Session Proposals

GCCE 2017 welcomes Organized Session (OS) proposals which are related to up-to-date and crossfield topics, except Regular Session Topics. Please fill out the Proposal Form on the web and send us at support@ieee-gcce.org!

Regular Session Topics & Keywords

The topics covered by GCCE 2017 include, but are not limited to,

- **TV & Display Technologies**
  - Future TV, Mobile TV, Ultra HDTV, Super Resolution Signal Processing, Network TV, Smart TV, 3D Imaging and Display, OEL, VoD, Visual Media Communication

- **Wireless & RF in CE**

- **Mobile Computing & Communications**
  - Mobile Broadband, Handheld and Wearable Computers, Personal Multimedia Devices, AV Streaming to Handheld Devices, Next-Generation Cellular Phones, Smart Phone Technologies

- **User Interfaces & Experience in CE**
  - Gesture Operation, Multitouch, Natural User Interface, Haptics, User Experience, HCI for CE, Usability, User Centered Design, Accessibility, Special-Needs/Assistive Technology

- **Storage & Digital Media**
  - Optical Storage, Magnetic Storage, Next-generation Storage Media, Semiconductors, Storage Technology, Cloud Media, Interactive Media, CE and Cloud Computing

- **Home Medical & Healthcare**
  - Home Medical Equipment, Medical IT/ICT, Healthcare Applications, Wellness Devices

- **Green Energy**
  - Solar Cell, Wind-generated Electricity for CE, Rechargeable Energy, Energy Harvesting

- **AV Processing & Streaming**

- **Home Networks & Services**
  - Wired and Wireless Networks at Home, Home Gateway, QoS, Bridges, Peer-to-Peer, Interoperability, Application Control, PVR, Home Theater, Interconnects, Gaming Devices and Systems, Internet Integration

- **Automotive Entertainment & Information**
  - Navigation, Driver Assistance, Car AV Systems, In-Car Internet, Communication Aspects, Automotive UI, Automotive Sensors and Controls

- **Security & Rights Management**
  - Copy and Redistribution Protection, Payments, Parental Controls, CE and Digital Content Issues, Data Collection, Biometrics, Privacy, Encryption

- **Smart Grid & CE**
  - Smart House, HEMS, BEMS, FEMS, CEMS, Smart Meter, Power Monitors, Energy Storage, On-site Power Generation, Sensors and Networks for Smart Grid, Internet of Things

- **Embedded Technologies**
  - Embedded Systems, Embedded OS, Embedded Software, High-density Mounting, Advanced Semiconductors, Development Tools

- **Enabling Technologies**